

RELIABILITY REPORT





NOW PART OF



Reliability Data Report

Product Family R503

LTC4151 / LTC6101 / LTC6102 /
LTC6103 / LTC6104

Reliability Data Report

Report Number: R503

Report generated on: Mon Mar 05 10:53:20 PST 2018

OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C) ¹	No. of FAILURES ^{2,3}
QFN/DFN	154	0719	0837	154	0
SOIC/MSOP	16979	0650	1615	1396	0
SOT	77	0502	0502	77	0
Totals	17,210	-	-	1,627	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	148	0737	0906	3	0
SOIC/MSOP	5510	0635	1713	273	0
SOT	13931	0510	1711	456	0
Totals	19,589	-	-	732	0

TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	146	0737	0906	14	0
SOIC/MSOP	4501	0710	1713	865	0
SOT	6816	0501	1711	979	0
Totals	11,463	-	-	1,858	0

THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	144	0737	0906	14	0
SOIC/MSOP	4625	0710	1713	669	0
SOT	9281	0510	1711	1200	0
Totals	14,050	-	-	1,883	0

HIGH TEMPERATURE BAKE AT 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	50	1018	1018	25	0
SOIC/MSOP	186	0814	1627	186	0
SOT	417	0815	0850	417	0
Totals	653	-	-	628	0

(1) Assumes Activation Energy = 0.7 Electron Volts

(2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =7.28 FITS

(3) Mean Time Between Failure in Years = 15674.71

Note 1: 1 FIT = 1 Failure in One Billion Hours.

Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning

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HIGH TEMPERATURE BAKE AT 175 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
SOIC/MSOP	77	0905	0905	77	0
Totals	77	-	-	77	0